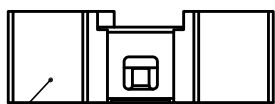
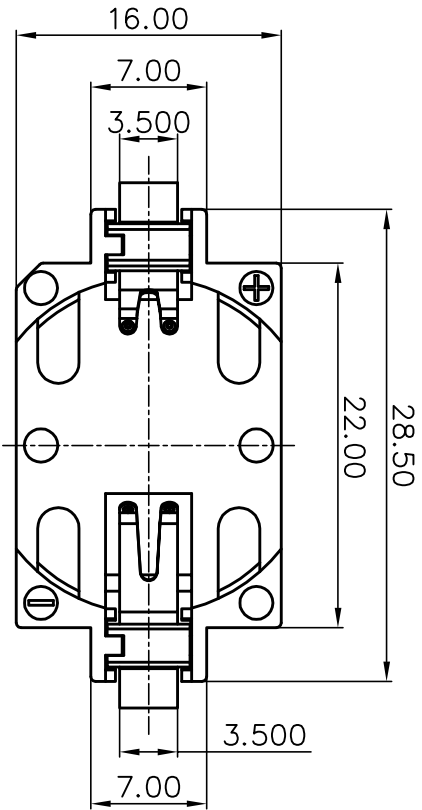
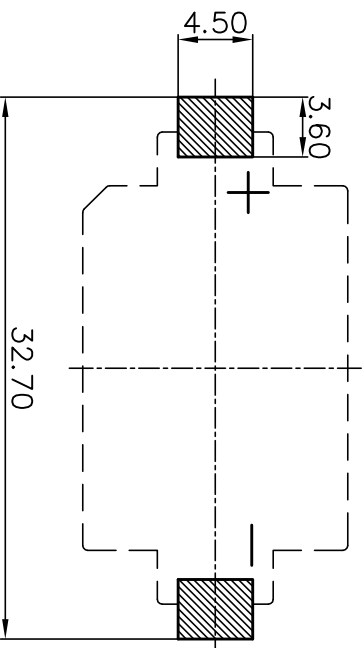
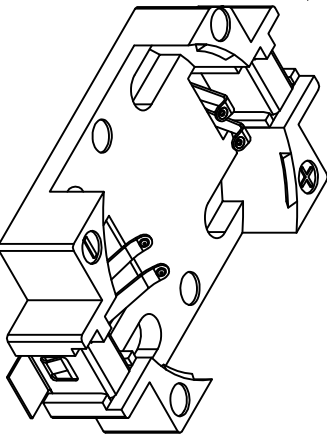
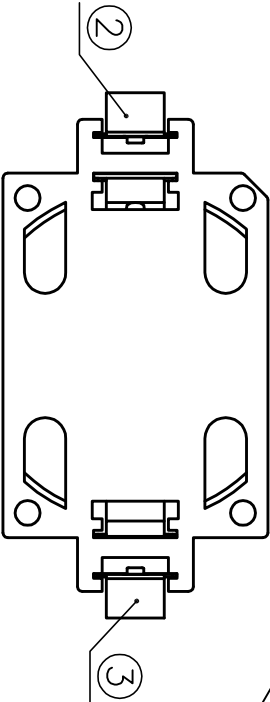
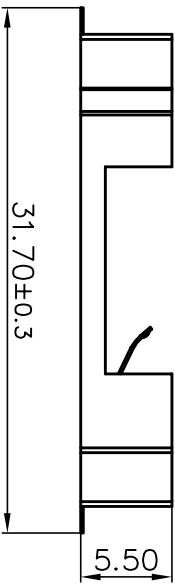


ROHS



1. MATERIAL:
 a. HOUSING: LCP
 b. CONTACT: PHOSPHOR BRONZE
 (SURFACE PLATING: Au1u")
2. ELECTRIC:
 a. CONTACT RESISTANCE: 30 MILLIOHMS MAX
 b. INSULATION RESISTANCE: 1000 MEGA OHMS MIN
 c. DIELECTRIC VOLTAGE: 500V AC ONE SEC LEVEL
 d. OPERATING TEMPERATURE: -25°C ~ +85°C



PCB Layout Diagram
 Top View

ECN NO.	REV	DATE	DESCRIPTION	CHANGE CHECK	APPRO

NO.	PART NAME	Q'TY	MATERIAL	PLATING & COLOR
③	TERMINAL(-)	1	PHOSPHOR BRONZE, T=0.15mm	Gold Plating and Ni Under-Plating
②	TERMINAL(+)	1	PHOSPHOR BRONZE, T=0.15mm	Gold Plating and Ni Under-Plating
①	HOUSING	1	LCP	WHITE

UNLESS OTHERWISE SPECIFIED TOLERANCES
 DECIMALS: ANGLES:
 X.X : ±0.30 X : ±1°
 X.XX : ±0.25 X.XX : ±0.5°
 X.XXX : ±0.20
 X.XXX : ±0.10

WEIGHT: 9

SHEET 1 OF 1

MeiYang Electronics Co.Ltd		TITLE:	
DSND LQ.HUANG	DATE 20180917	APVD XY.XUE	DATE 20180917
CHKD	DATE	SCALE: A4	VIEW: ④
UNIT:mm	REV:A/0	OBJE:MY	DRAW NO:MY-CP-0014
PART NO.:		BS-2032-6 Au SMT	
PART NO.:		BS-06-B4AA002	